

v00 0600

HMC288MS8

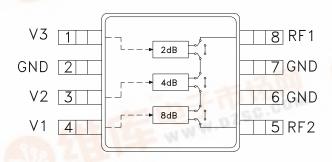
2 dB LSB GaAs MMIC 3-BIT DIGITAL ATTENUATOR, 0.7 - 3.7 GHz

Typical Applications

The HMC288MS8 is ideal for:

- Cellular
- PCS, ISM, MMDS
- WLL applications

Functional Diagram



Features

2 dB LSB Steps to 14 dB
Single Positive Control Per BIT
Monotonic: ±03 dB Bit Error Typical
Miniature MSOP-8 Package, 14.8mm²

General Description

The HMC288MS8 is a broadband 3-bit positive control GaAs IC digital attenuator in an 8 lead MSOP surface mount plastic package. Covering 0.7 to 3.7 GHz, the insertion loss is typically less than 1.2 to 1.8 dB. The attenuator bit values are 2 (LSB), 4, and 8 dB for a total attenuation of 14 dB. Accuracy is excellent at ± 0.3 dB typical with an IIP3 of up to +51 dBm. Three bit control voltage inputs, toggled between 0 and +3 to +5V, are used to select each attenuation state at less than 50 uA each. A single Vdd bias of +3 to +5V applied through an external 5K Ohm resistor is required while occupying less than 14.8 mm².

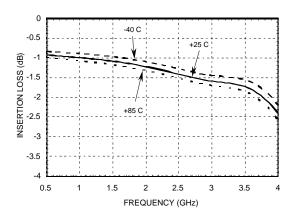
Electrical Specifications,

 $T_A = +25^{\circ} \text{ C}$, Vdd = +3V to +5V & Vctl = O/Vdd (Unless Otherwise Stated)

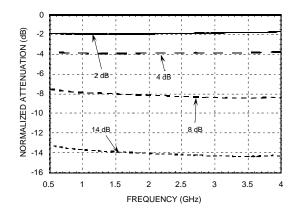
Parameter	Frequency	Min.	Typical	Max.	Units
Insertion Loss	0.7 - 1.4 GHz 1.4 - 2.3 GHz 2.3 - 2.7 GHz 2.7 - 3.7 GHz		1.0 1.3 1.5 1.7	1.4 1.7 2.0 2.3	dB dB dB dB
Attenuation Range	0.7 - 3.7 GHz		14		dB
Return Loss (RF1 & RF2, All Atten. States)	0.7 - 1.4 GHz 1.4 - 2.3 GHz 2.3 - 2.7 GHz 2.7 - 3.7 GHz	14 11 10 9	17 15 14 12	DZSC	dB dB dB dB
Attenuation Accuracy: (Referenced to Insertion Loss) All Attenuation States	0.7 - 1.4 GHz 1.4 - 2.3 GHz 2.3 - 2.7 GHz 2.7 - 3.7 GHz	± 0.3 + 3% of Atten. Setting Max ± 0.2 + 3% of Atten. Setting Max ± 0.3 + 3% of Atten. Setting Max ± 0.3 + 4% of Atten. Setting Max		dB dB dB dB	
Input Power for 0.1 dB Compression 5V 3V	0.7 - 3.7 GHz		25 22		dBm dBm
Input Third Order Intercept Point 5V (Two-tone Input Power = 0dBm Each Tone) 3V	0.7 - 3.7 GHz		51 47		dBm dBm
Switching Characteristics	0.7 - 3.7 GHz				
IRISE, IFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)			560 600		ns ns



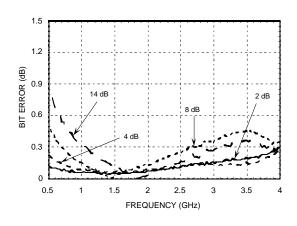
Insertion Loss



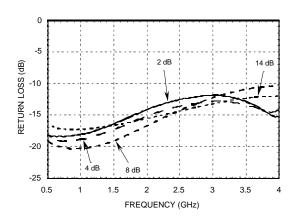
Normalized Attenuation (Only Major States are Shown)



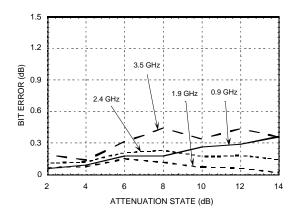
Absolute Bit Error vs. Frequency (Only Major States are Shown)



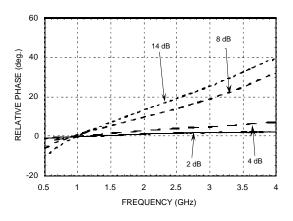
Return Loss RF1, RF2 (Only Major States are Shown)



Absolute Bit Error vs. Attenuation State



Relative Phase vs. Frequency (Only Major States are Shown)



Note: All Data Typical Over Voltage (+3V to +5V) & Temperature (-40 to +85 deg. C.).



Truth Table

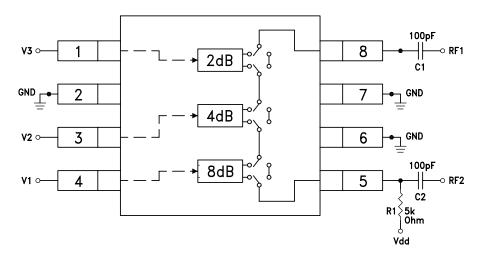
Control Voltage Input			Attenuation	
V1 8 dB	V2 4 dB	V3 2 dB	Setting RF1 - RF2	
High	High	High	Reference I.L.	
High	High	Low	2 dB	
High	Low	High	4 dB	
Low	High	High	8 dB	
Low	Low	Low	14 dB Max. Atten.	

Any combination of the above states will provide an attenuation approximately equal to the sum of the bits selected.

Control & Bias Voltages

State	Bias Condition	
Low	0 to +0.2V @ 20 uA Max.	
High	High Vdd ± 0.2V @ 50 uA Max	
Note: $Vdd = +3V$ to $5V \pm 0.2V$		

Application Circuit



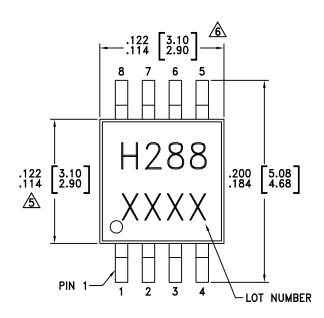
DC blocking capacitors C1 & C2 are required on RF1 & RF2. Choose C1 = C2 = $100 \sim 300$ pF to allow lowest customer specific frequency to pass with minimal loss. R1 = 5K Ohm is required to supply voltage to the circuit throught either PIN 5 or PIN 8.

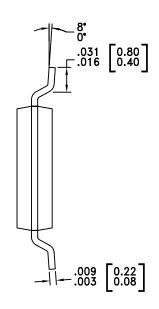


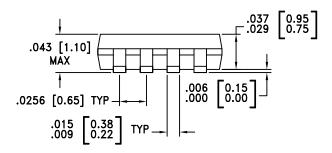
Absolute Maximum Ratings

Control Voltage (V1, V2, V3)	Vdd + 0.5 Vdc
Bias Voltage (Vdd)	+8.0 Vdc
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
RF Input Power (0.7 - 4 GHz)	+28 dBm

Outline Drawing







NOTES

- PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEADFRAME MATERIAL: COPPER ALLOY
- 3. LEADFRAME PLATING: Sn/Pb SOLDER
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].

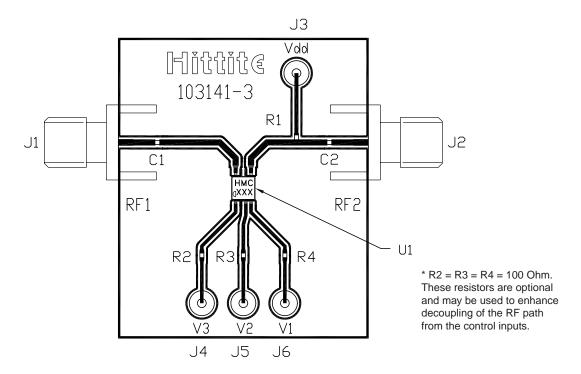
DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.

DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.

7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.



Evaluation Circuit Board



The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown . A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation circuit board as shown is available from Hittite Microwave Corporation upon request.

List of Material

Item	Description	
J1 - J2	PC Mount SMA Connector	
J3 - J6	DC Pin	
R1	5k Ohm Resistor, 0402 Chip	
R2, R3, R4	100 Ohm Resistor, 0402 Chip	
C1, C2	0402 Chip Capacitor, Select for Lowest Frequency of Operation	
U1	HMC288MS8 Digital Attenuator	
PCB*	103141 Evaluation PCB 1.5" x 1.5"	
*Circuit Board Material: Rogers 4350		





MICROWAVE CORPORATION

2 dB LSB GaAs MMIC 3-BIT DIGITAL ATTENUATOR, 0.7 - 3.7 GHz

Notes: